PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Satoshi Kawanaka	12/18/2007
Atsushi Nakamura	12/18/2007
Masato Hagimoto	12/18/2007
Hideki Hara	12/18/2007
Masakatsu Yamamoto	12/18/2007

RECEIVING PARTY DATA

Name:	Opnext Japan, Inc.
Street Address:	216, Totsuka-cho, Totsuka-ku, Yokahama-shi,
City:	Kanagawa
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12023168

OP $40.00 12023168

CORRESPONDENCE DATA

Fax Number: (703)312-6666
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 703-312-6600
Email: rrodriguez@antonelli.com
Correspondent Name: Antonelli, Terry, Stout & Kraus, LLP
Address Line 1: 1300 N. 17th Street
Address Line 2: Suite 1800
Address Line 4: Arlington, VIRGINIA 22209

ATTORNEY DOCKET NUMBER:	501.48364X00
NAME OF SUBMITTER:	Gregory E. Montone

Total Attachments: 1

ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Opnext Japan, Inc.,
a corporation organized under the laws of Japan,
located at 216, Totsuka-cho, Totsuka-ku, Yokohama-shi, Kanagawa, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Opnext Japan, Inc.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR LASER DIODE AND ITS FABRICATION PROCESS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Opnext Japan, Inc.,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Opnext Japan, Inc.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Satoshi Kawanaka	12/18/2007
2)	Atsushi Nakamura	12/18/2007
3)	Masato Hagimoto	12/18/2007
4)	Hideki Hara	12/18/2007
5)	Masakatsu Yamamoto	12/18/2007
6)		
7)		
8)		
9)		
10)		